

ASMPT Announces 2026 First Quarter Results

Strong Demand Driven by AI

Group Performance at a Glance

Key Highlights

- * Multiple products benefitting from AI technology evolution
- * Group quarterly bookings exceed expectations; SMT bookings at record level
- * SEMI adjusted gross margin hit 46.4%, driven by product mix
- * Revenue and adjusted EPS above market consensus

Group Results Summary

(in HK\$ million)	Q1 2026	QoQ	YoY
	Continuing Operations		
Bookings	5,673.4 (US\$727.0 million)	+46.0%	+71.6%
Revenue	3,966.8 (US\$507.9 million)	+0.2%	+32.0%
Gross Margin	39.5%	+364bps	-150bps
Operating Profit	385.2	+139.2%	+105.6%
Net Profit	323.8	-70.8%	+192.9%
Basic Earnings Per Share	HK\$0.78	-70.8%	+188.9%
	Non-HKFRS Measures² of Continuing Operations		
Adjusted Gross Margin	39.5%	+357bps	-151bps
Adjusted Operating Profit	395.7	+103.2%	+107.4%
Adjusted Net Profit	335.2	+123.8%	+193.5%
Adjusted Basic Earnings Per Share	HK\$0.81	+118.9%	+189.3%

(in HK\$ million)	Q1 2026	QoQ	YoY
	Discontinued¹ Operation		
Net Loss	(72.6)	-53.5%	+159.6%
Adjusted Net Loss (Non-HKFRS Measures²)	(72.6)	NM	+159.9%

NM: Not meaningful

(in HK\$ million)	Q1 2026	QoQ	YoY
	Continuing and Discontinued¹ Operations		
Net Profit	251.2	-73.7%	+204.1%
Basic Earnings Per Share	HK\$0.61	-73.5%	+205.0%
	Non-HKFRS Measures² of Continuing and Discontinued¹ Operations		
Adjusted Net Profit	262.6	+24.1%	+204.4%
Adjusted Basic Earnings Per Share	HK\$0.64	+23.1%	+204.8%

Revenue Guidance for Q2 2026

* US\$540 million to US\$600 million, up 12.2% QoQ and 37.0% YoY at mid-point of US\$570 million

Full Results Announcement and Investor Presentation available from:
<https://www.asmpt.com/en/investor-relations/financial-information/>

¹ As disclosed by the Group in Q4 2025, the Group has decided to divest ASMPT NEXX, Inc. ("NEXX"), which has been classified as a Discontinued Operation. As at the date of the Group's Q1 2026 results announcement, no binding agreement has been entered into for the proposed divestment. Further updates will be provided as required under applicable disclosure obligations.

² For more information about the Non-HKFRS Measures presented above, please refer to the section under "Reconciliation of HKFRS Measures to the non-HKFRS Measures" of the Group's Q1 2026 results announcement.

(Hong Kong, 22 April 2026) — **ASMPT Limited** (ASMPT / the Group / the Company) (Stock code: 0522), a leading global provider of hardware and software solutions for the manufacture of semiconductors and electronics, announced its first quarter results for the three months ended 31 March 2026. As the AI landscape evolves, the Group is seeing a significant shift of both value and complexity into backend semiconductor manufacturing, supporting broad-based demand for its comprehensive suite of solutions. Meanwhile, AI infrastructure buildouts continue to support SEMI and SMT mainstream applications with increasing power density and reliability requirements.

Mr. Robin Ng, Group CEO: "We delivered one of our strongest quarters in recent years. Notably, we are seeing just how broadly AI demand is translating into more opportunities across multiple products and customer segments in ASMPT – including TCB, photonics & CPO, and our mainstream platforms. As the value and complexity of backend manufacturing increases, ASMPT is well-positioned to play a critical role as AI moves increasingly from innovation into broad deployment."

The following review will include the Group's Continuing Operations only, after adjustments under non-HKFRS measures, unless otherwise specified.

Group Q1 2026 Highlights

The rapid evolution of AI technology is increasing the value and complexity of backend semiconductor manufacturing. New AI Architectures demand heterogeneous integration, tighter interconnect pitch, higher bandwidth and power efficiency across data-centre, cloud and edge workloads. These requirements are driving higher precision, alignment and process-control needs across packaging flows, increasing demand for the Group's solutions, which include Thermo-Compression Bonding (TCB) and Hybrid Bonding (HB) for advanced logic-to-memory interconnects, high-precision Flip Chip and Mass Reflow for cost-efficient scaling, and Photonics & Co-Packaged Optics (CPO) as connectivity constraints emerge. In parallel, AI-infrastructure build-outs continue to support SEMI and SMT mainstream applications with increasing power density and reliability requirements.

- Group revenue of HK\$3.97 billion (US\$507.9 million) was above mid-point of guidance, up 0.2% QoQ and 32.0% YoY.
- Group bookings of HK\$5.67 billion (US\$727.0 million) were up 46.0% QoQ and 71.6% YoY, significantly stronger than expected and the highest in the last 4 years. The book-to-bill ratio was 1.43. Growth came from multiple products, notably SMT, wire & die bonders, and Photonics.
- Group adjusted gross margin of 39.5% was up 357 bps QoQ but down 151 bps YoY. QoQ improvement was due to higher gross margin and revenue contribution from SEMI, while the YoY drop was due higher revenue contribution from SMT.
- Group adjusted operating expenses (OPEX) were down 4.6% QoQ mainly due to cost control measures. Adjusted OPEX was up 12.4% YoY largely due to unfavourable FX impact, strategic infrastructure and R&D investments.
- Adjusted net profit was HK\$335.2 million, up 123.8% QoQ and 193.5% YoY, due to higher operating profit.

TCB: In Logic, the Group further solidified its leadership in chip-to-substrate (C2S), through sizeable shipments and repeat orders in Q1. For chip-to-wafer (C2W), the Group booked a total of four tools in Q1 for its ultrafine-pitch TCB solution featuring the Group's proprietary plasma AOR technology from a leading advanced logic customer. The Group is also actively collaborating with key logic players across multiple programmes and is well-positioned for more opportunities as the industry advances towards more complex logic chip architectures.

In Memory, the Group remains at the forefront of technology development, with a key memory player adopting its flux based TCB tool for sampling and qualifying the Group's AOR fluxless process for HBM4 16H.

Photonics & CPO: The Group's Photonics solutions achieved a five-fold increase in YoY revenue growth, propelled by strong demand from high-speed transceivers of 800G and beyond. Notably, its 1.6T transceiver solutions received bulk orders from key optics suppliers in the data centre networking supply chain. This demonstrates strong traction for the Group's optical transceiver solutions as the market leader. In CPO, the Group deepened engagements with multiple leading global CPO players, positioning it well to gain market share as CPO adoption accelerates.

Flip Chip High Precision Die-Bonding (FC): The Group's FC solutions achieved strong bookings growth. The rapid adoption of 2.5D packaging for larger AI package sizes has led to a steady order pipeline for the Group's FC solutions for embedded bridge die bonding across both Chip-on-Wafer (CoW) and Chip-on-Panel (CoP) applications. The Group's solutions are also gaining traction in Panel-Level Fan-Out (PLFO) for radio frequency and power devices. These solutions offer cost effectiveness, scalability, and both superior placement accuracy and throughput.

SEMI Mainstream: SEMI's mainstream business benefitted from sustained utilisation at leading global IDMs and OSATs, and increased demand for power management solutions for AI data centres. In China, the mainstream business saw increased demand for wire and die bonding applications due to AI infrastructure capacity expansion and robust OSAT utilisation.

SMT: SMT delivered record bookings in Q1, driven by strong demand from AI servers, optical transceivers and China EVs. In particular, SMT's high flex, high force solutions for large format boards are a leading choice for AI server assembly, combining fast pick-and-place of large, heavy components with high-density, multi-angle placement & enhanced inspection capabilities to drive superior yield and throughput.

Outlook

The Group expects Q2 2026 revenue to be between US\$540 million to US\$600 million, up 12.2% QoQ and 37.0% YoY at mid-point of US\$570 million, which is above market consensus. This strong growth will be driven mainly by SEMI.

The Group expects bookings in Q2 2026 to remain elevated for both segments, though SMT will be down QoQ due to high base effect.

The continued proliferation of AI is expected to drive broad-based, structural demand for ASMPT across multiple products. These include the Group's cutting-edge TCB and HB solutions enabling next-generation AI compute and HBM, photonics and CPO supporting

high-speed data requirements, to wire & die bonding and pick-and-place solutions enabling AI infrastructure deployment. Looking ahead, structural AI-driven demand is expected to support revenue growth across both SEMI and SMT in 2026.

While the Group has not experienced any material impact from the ongoing geopolitical developments in the Middle East, it acknowledges that uncertainties remain. The Group's global presence provides it with the flexibility to navigate any potential impact, and it will continue to monitor the situation closely and adapt as needed.

About ASMPT Limited (ASMPT)

ASMPT Limited is a leading global supplier of hardware and software solutions for the manufacture of semiconductors and electronics. Headquartered in Singapore, ASMPT's offerings encompass the semiconductor assembly & packaging, and SMT (surface mount technology) industries, ranging from wafer deposition to the various solutions that organise, assemble and package delicate electronic components into a vast range of end-user devices. ASMPT partners with customers very closely, with continuous investment in R&D helping to provide cost-effective, industry-shaping solutions that achieve higher productivity, greater reliability, and enhanced quality. ASMPT is also a founding member of the [Semiconductor Climate Consortium](#).

ASMPT is listed on the Stock Exchange of Hong Kong (HKEX stock code: 0522) and is one of the constituent stocks of the HKEX Tech 100 Index, Hang Seng Composite MidCap Index under the Hang Seng Composite Size Indexes, the Hang Seng Composite Information Technology Industry Index under Hang Seng Composite Industry Indexes, the Hang Seng Corporate Sustainability Benchmark Index, and the Hang Seng HK 35 Index. To learn more about ASMPT, please visit us at <http://www.asmpt.com>.

Forward-Looking Statements

All statements included herein, other than statements of historical facts, are or may be forward-looking statements. These forward-looking statements reflect ASMPT's current expectations, beliefs, hopes, intentions or strategies regarding the future and assumptions in light of currently available information. Such forward-looking statements are not guarantees of future performance or events and involve known or unknown risks and uncertainties. Accordingly, actual results may differ materially from information contained in the forward-looking statements as a result of a number of factors. Readers should not place undue reliance on such forward-looking statements, and ASMPT does not undertake any obligation to update publicly or revise any forward-looking statements. Save as otherwise referred to below, no statement herein is intended to be or may be construed as a profit forecast.

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